

The 21<sup>st</sup> Korean Conference on Semiconductors  
**제21회 한국반도체학술대회**  
February 24–26, 2014 / Hanyang University, Seoul, Korea

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A. Interconnect & Package 분과

**[WC1-A] High Performance Mobile Packaging Technology**

<b>Date</b>	Feb. 26, 2014 (Wed.)
<b>Place</b>	Room C / 제1공학관 401호 (# 401, Engineering Building I)

Session Chair: 이용선 박사(SK hynix),

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- WC1-A-1**    **10:50-11:20**    **SI/PI Co-Simulation Including Voltage Regulating Circuitry for High-Performance Multi-Chip Packages**  
저자: JuHwan Lim, JongJoo Lee, SoYoung Jung, and JoonHee Lee  
소속: Memory Division, Samsung Electronics Co., Ltd.
- WC1-A-2**    **11:20-11:35**    **전류 보조 접합 방법에 의한 Cu-Cu 직접 접합 방법**  
저자: 마성우<sup>1</sup>, 신찬호<sup>1</sup>, 안기원<sup>2</sup>, 이정환<sup>3</sup>, 김기범<sup>3</sup>, 서민석<sup>3</sup>, 변광유<sup>3</sup>, 김영호<sup>1,2</sup>  
소속: <sup>1</sup>한양대학교 나노반도체공학과, <sup>2</sup>한양대학교 신소재공학부, <sup>3</sup>SK 하이닉스 반도체
- WC1-A-3**    **11:35-11:50**    **Parametric Study for Optimum Ag wire Bondability**  
저자: Kwang-Soo Kim, Jae-Seung Seok, Kyung-Man Kim, Sung-Wook Hwang, Hai-Ick Kim, Joon-Young Oh, and Joon-Hee Lee  
소속: Flash Development, Samsung Electronics Co., Ltd.
- WC1-A-4**    **11:50-12:05**    **40 um Pitch Micro Bump의 Interconnection 평가**  
저자: Seunghyun Lee, Seongkwon Chin, Sukwoo Jeon, and Namseog Kim  
소속: SK hynix Inc.